

LISTINGS OF THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A housing having a liquid-tight electric bushing comprising:
an opening in the housing; and
~~a closure for the opening, the closure comprising~~ a printed circuit board mounted to the housing and having at least first and second layers, the at least first and second layers being configured without a continuous opening such that the printed circuit board is a liquid-tight closure that prevents a liquid from flowing into the opening; the first layer ~~being~~ is a top side of the printed circuit board ~~that and~~ spans the opening and the second layer being a conductor track in the interior of the printed circuit board,
wherein a first contact element is disposed on the top side and in a bore through the first layer that extends to at least the second layer, ~~and~~
~~wherein the second layer is a conductor track in the interior of the printed circuit board.~~
2. (Cancelled)
3. (Cancelled)
4. (Previously Presented) The housing as defined by claim 1, wherein the first layer is an electrical insulation material.
5. (Previously Presented) The housing as defined by claim 1, wherein the first contact element is coupled to a second contact element via the second layer.
6. (Cancelled)

7. (Previously Presented) The housing as defined by claim 5, wherein the second contact element is on an underside that is opposite the top side.

8. (Previously Presented) The housing as defined by claim 5, wherein the second contact element extends to an outside an edge of the printed circuit board.

9. (Previously Presented) The housing as defined by claim 1, wherein the printed circuit board is flexible.

10. (Previously Presented) The housing as defined by claim 1, wherein the printed circuit board comprises a plurality of second layers, located one above the other.

11. (Previously Presented) The housing as defined by claim 5, claims, wherein the first contact element and the second contact element are coupled via a plurality of conductor tracks, which are located one above the other and are electrically coupled.

12. (Previously Presented) The housing as defined by claim 1, wherein a seal is disposed between the printed circuit board and the housing.

13. (Previously Presented) The housing as defined by claim 12, wherein a pressure plate contacts the underside of the printed circuit board and presses the printed circuit board against the seal.

14. (Currently Amended) The housing as defined by claim 1, wherein the housing further comprises an X-ray tube.

15. (Currently Amended) A method of using a printed circuit board to close an opening provided in a housing and as an electric bushing comprising:

mounting the printed circuit board comprising a first layer on the housing, the printed circuit board having no continuous opening such that the printed circuit board is a liquid-

tight closure that prevents a liquid from flowing into the opening wherein the first layer spans the opening and is the top side of the printed circuit board, and

disposing a first contact element on the top side and through a bore in the top side, wherein the bore extends to at least ~~as far as~~ a second layer formed in the printed circuit board, the second layer being as a conductor track.

16. (Cancelled)

17. (Cancelled)

18. (Previously Presented) The method as defined by claim 15, wherein the method further includes producing the first layer from an electrical insulation material.

19. (Previously Presented) The method as defined by claim 15, wherein the method further comprises connecting the first contact element to a second contact element via the second layer.

20. (Cancelled)

21. (Currently Amended) The method ~~use~~ as defined by claim 19, wherein the method further comprises disposing the second contact element on an underside that is opposite the top side.

22. (Previously Presented) The method as defined by claim 19, wherein the method further comprises extending the second contact element to an outside edge of the printed circuit board.

23. (Previously Presented) The method as defined by claim 15, wherein the method further comprises using the printed circuit board that is flexible.

24. (Previously Presented) The method as defined by claim 15, wherein the method comprises using the printed circuit board that has a plurality of second layers located one above the other

25. (Previously Presented) The method as defined by claim 24, wherein the first contact element and a second contact element are connected via a plurality of conductor tracks in alignment with each other.

26. (Previously Presented) The method ~~use~~ as defined by claim 15, wherein the method comprises disposing a seal between the printed circuit board and the housing.

27. (Previously Presented) The method as defined by claim 26, wherein the method comprises using a pressure plate that contacts the underside of the printed circuit board and presses the printed circuit board against the seal.

28. (Previously Presented) The method as defined by claim 15, wherein the method further comprises using an X-ray tube in the housing.